

**Bridge Rectifier Diode 整流桥****■Features 特点**

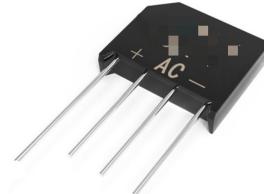
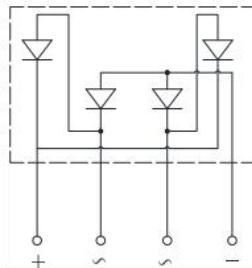
Low forward voltage 低正向压降

Low leakage current 低漏电流

Ideal for PCB 适用于印刷电路板

Solder dip 275°C 7S 焊接 275 度 7 秒内

Package 封装: KBP

**■Maximum Rating 最大额定值**

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	KBP306	KBP308	KBP310	Unit 单位
Peak Reverse Voltage 反向峰值电压	V <sub>RRM</sub>	600	800	1000	V
DC Reverse Voltage 直流反向电压	V <sub>R(DC)</sub>	600	800	1000	V
RMS Reverse Voltage 反向电压均方根值	V <sub>R(RMS)</sub>	420	560	700	V
Forward Rectified Current 正向整流电流	I <sub>F</sub>	3			A
Peak Surge Current 峰值浪涌电流	I <sub>FSM</sub>	80			A
Thermal Resistance J-A 结到环境热阻	R <sub>θJA</sub>	30			°C/W
Junction and Storage Temperature 结温和储藏温度	T <sub>J</sub> , T <sub>stg</sub>	150°C, -55 to +150°C			

**■Electrical Characteristics 电特性**

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Condition 条件
Forward Voltage 正向电压降	V <sub>F</sub>		1.1		V	I <sub>F</sub> =3A
Reverse Leakage Current 反向漏电流(T <sub>A</sub> =25°C)	I <sub>R</sub>			10 500	uA	V <sub>R</sub> =V <sub>RRM</sub>
Diode Capacitance 二极管电容	C <sub>D</sub>		25		pF	V <sub>R</sub> =4V, f=1MHz

### ■Typical Characteristic Curve 典型特性曲线

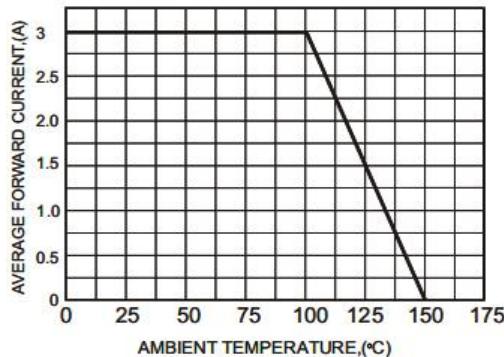


Figure 1: Forward Current Derating Curve

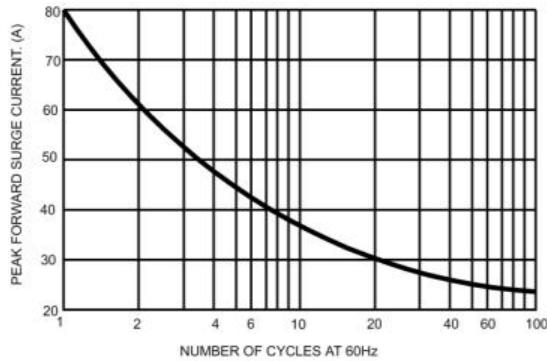


Figure 2: Peak Forward Surge Current

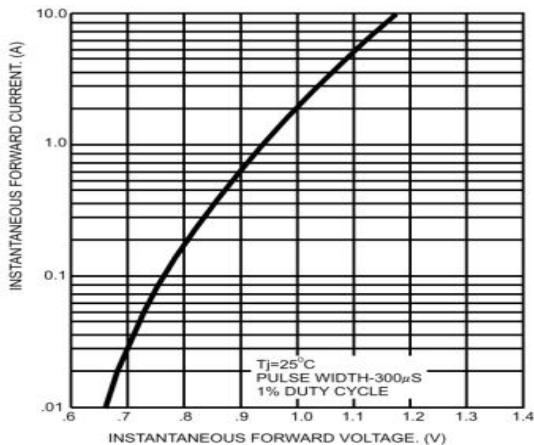


Figure 3: Instantaneous Forward Characteristics

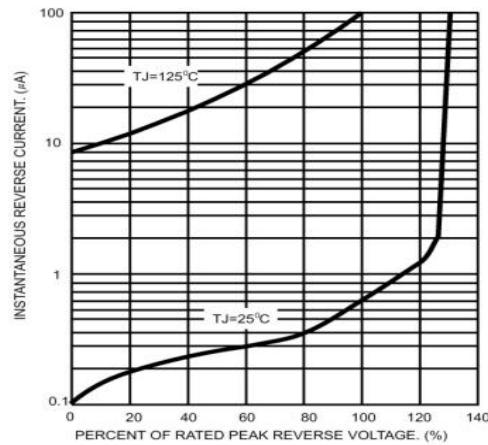


Figure 4: Reverse Leakage Characteristics

### ■Dimension 外形封装尺寸

